

ABSTRACT OF THE DISCLOSURE

[0035] A method of fabricating a component package for components such as integrated circuits and a component package. A carrier is molded to form a plurality of cavities. A lid is molded to define a vent hole corresponding to each of the cavities. Components, such as integrated circuit dies, are mounted on the carrier in each of the cavities. A curable adhesive is applied to the top of the sidewalls defining the cavities. The top cover is pressed against the top of the sidewalls with a vent hole aligned with each cavity. The adhesive is then cured under heat. The curing process not only cures the adhesive, it vents moisture from the cavities. The vent holes are then sealed using a curable adhesive. The assembly is cut into individual integrated circuit packages.